

TITLE: METHOD OF IMPROVING COPPER INTERCONNECTS OF
SEMICONDUCTOR DEVICES FOR BONDING

Inventor: Salman Akram
Docket No.: 3854.3US

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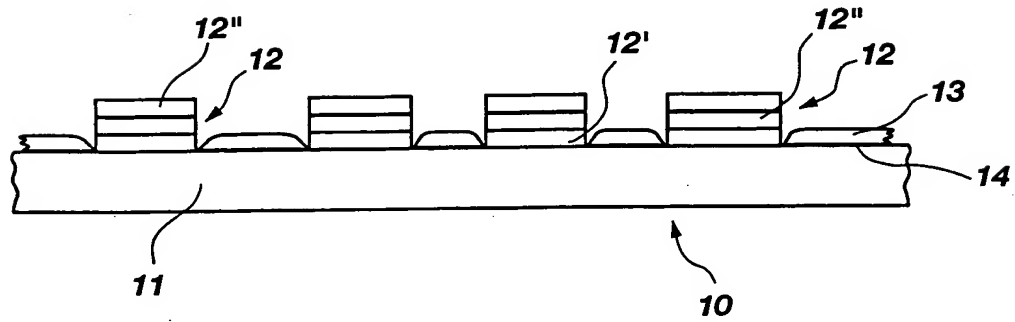


Fig. 1

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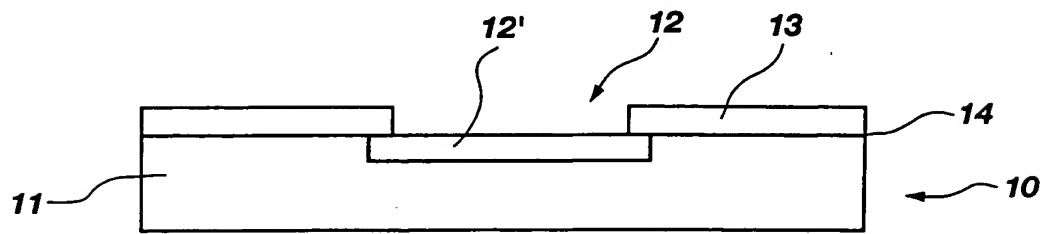


Fig. 2A

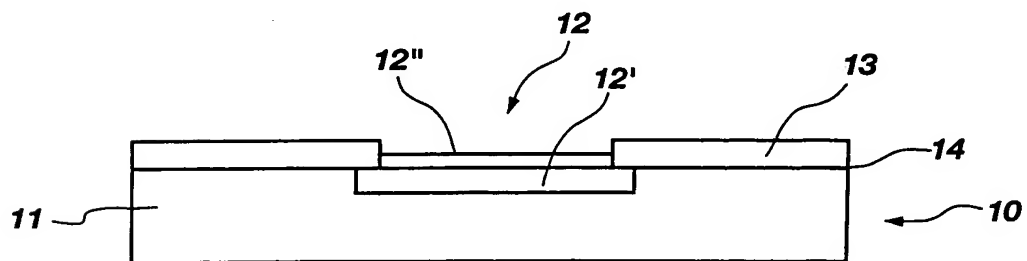


Fig. 2B

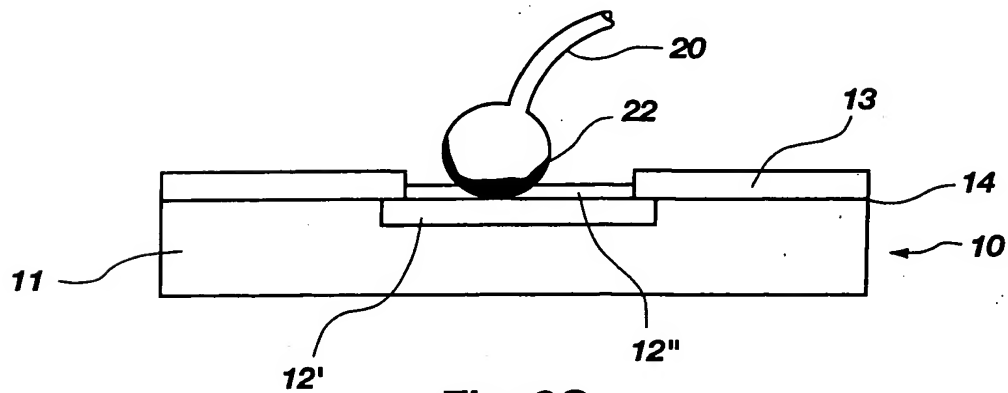


Fig. 2C

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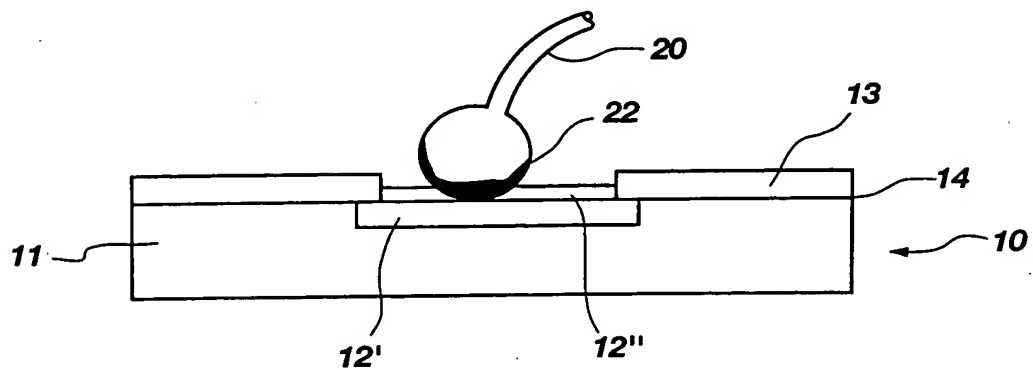


Fig. 2D

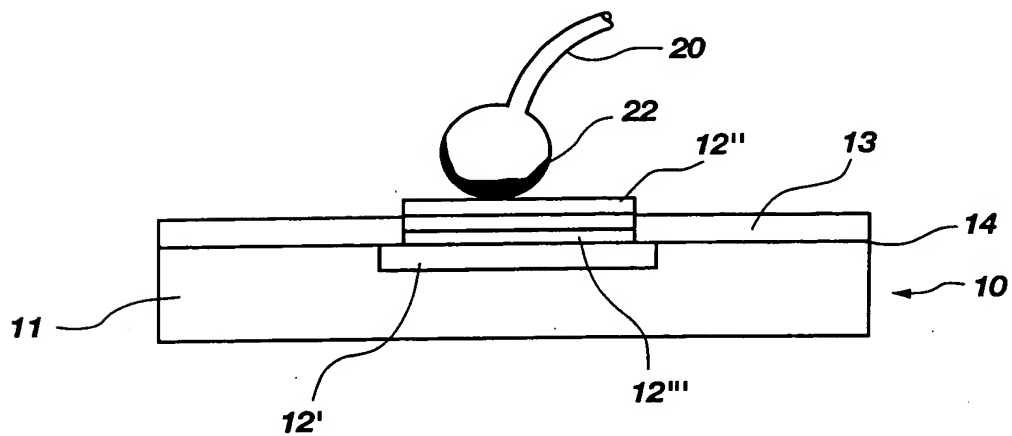


Fig. 2E

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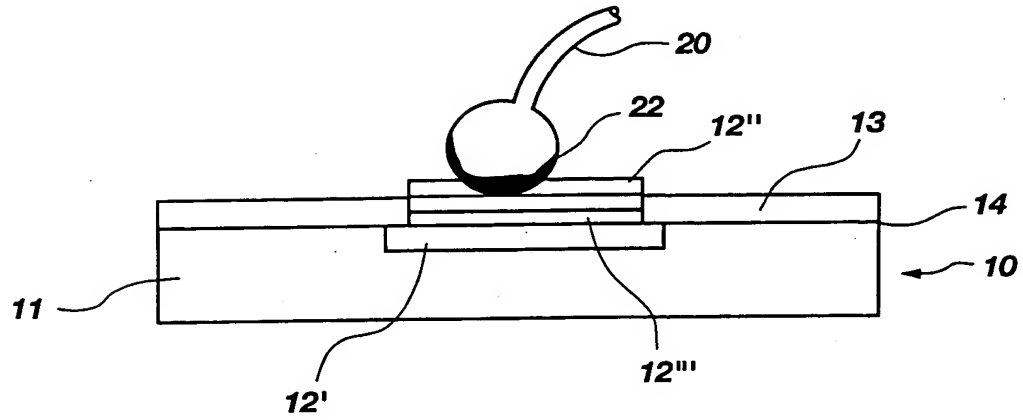


Fig. 2F

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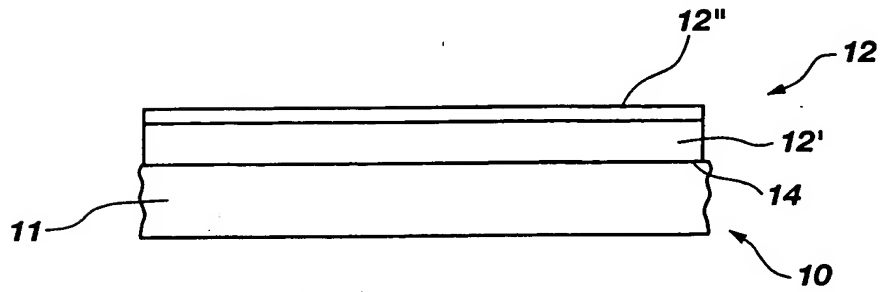


Fig. 3A

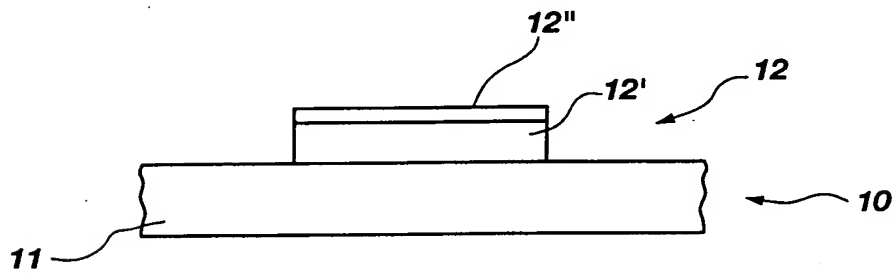


Fig. 3B

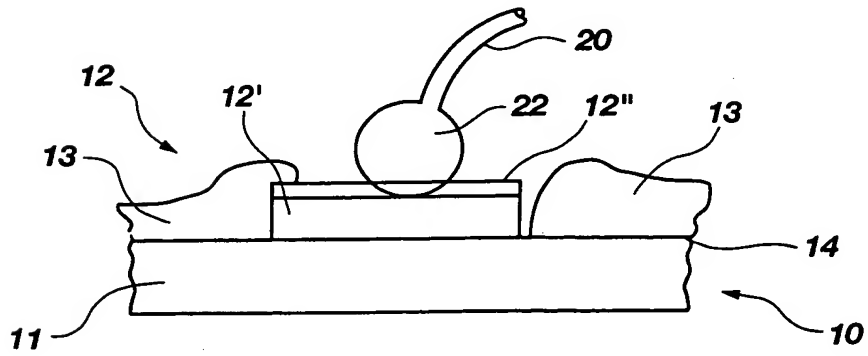


Fig. 3C

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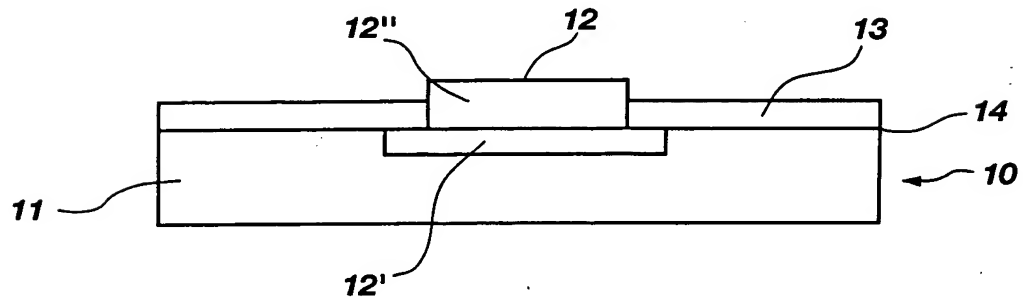


Fig. 4A

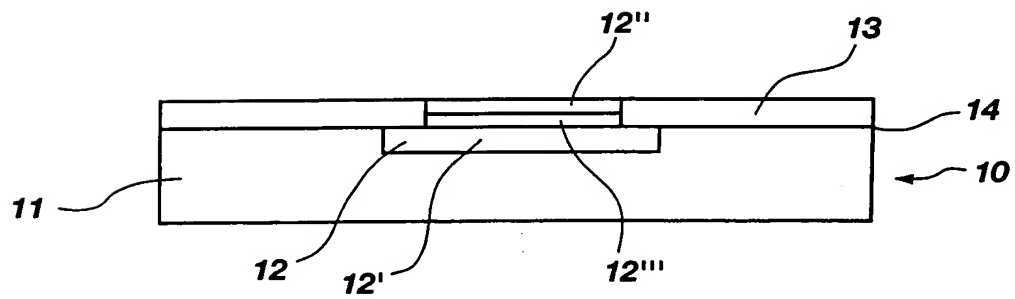


Fig. 4B

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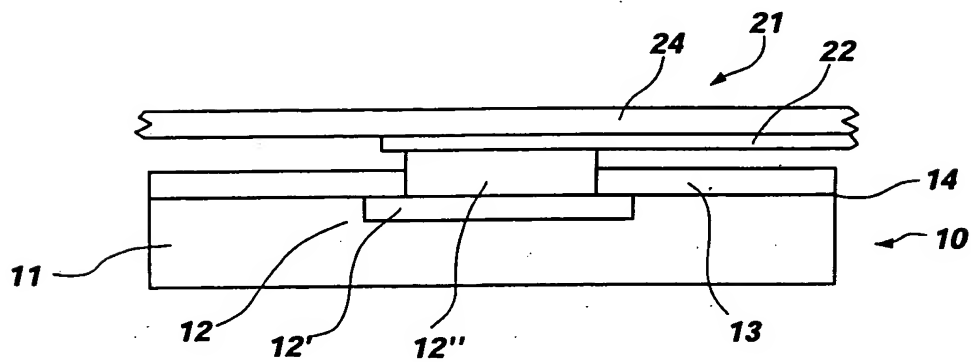


Fig. 4C

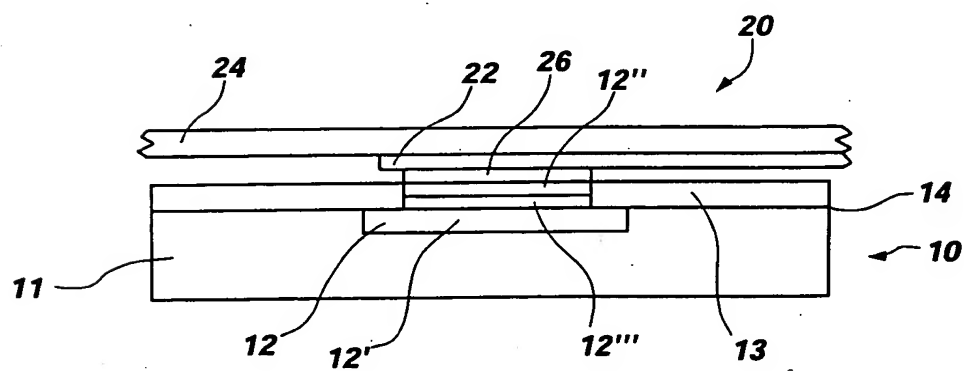


Fig. 4D

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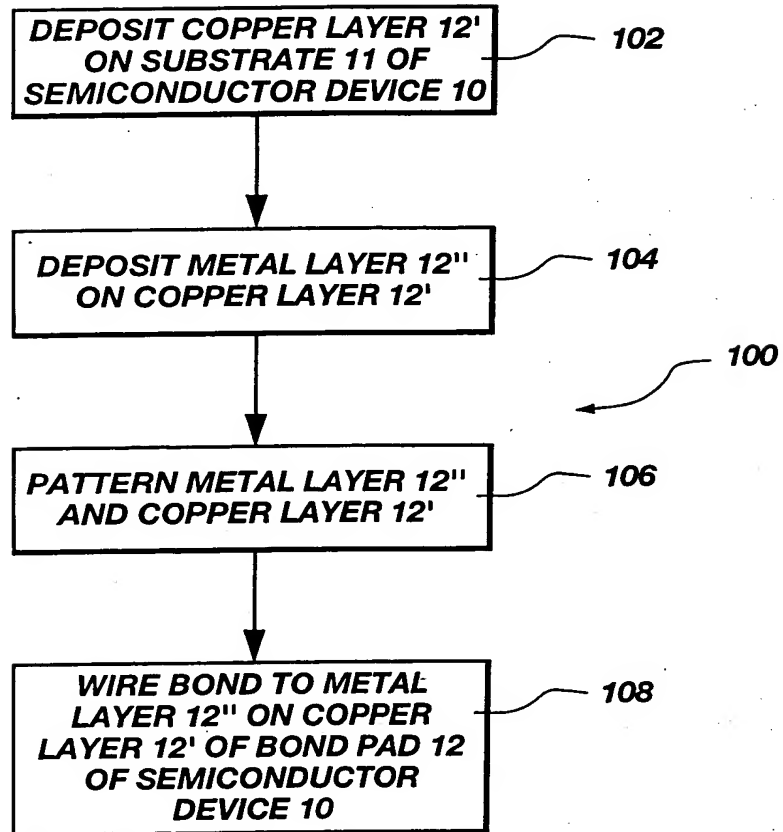


Fig. 5A

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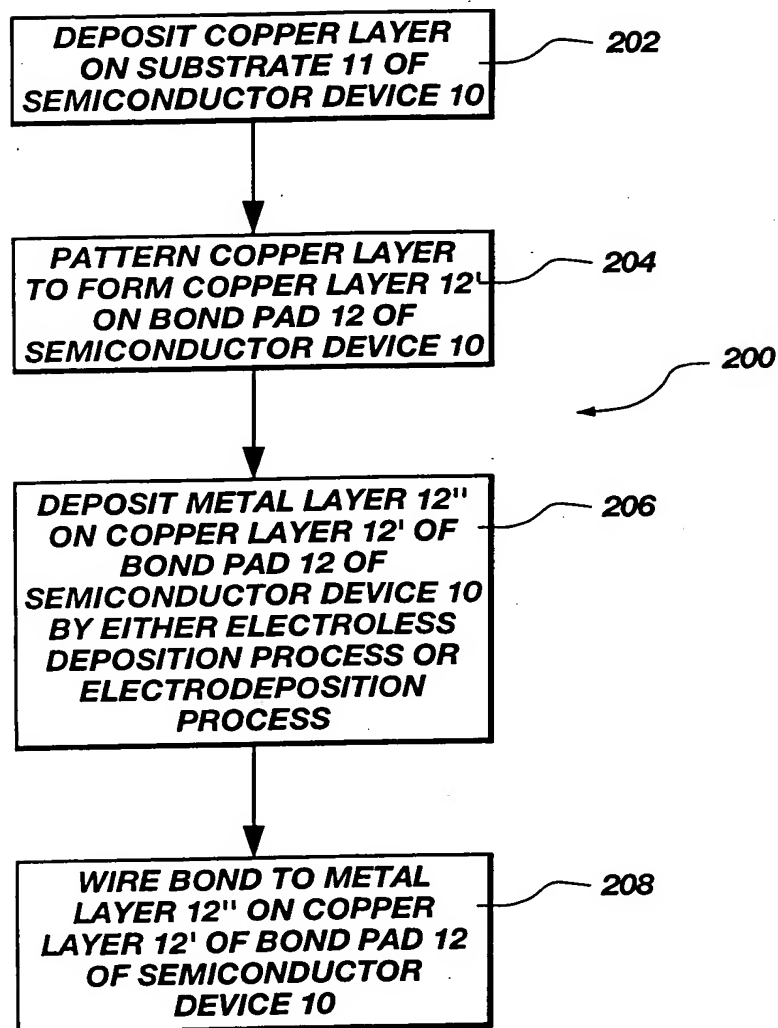


Fig. 5B

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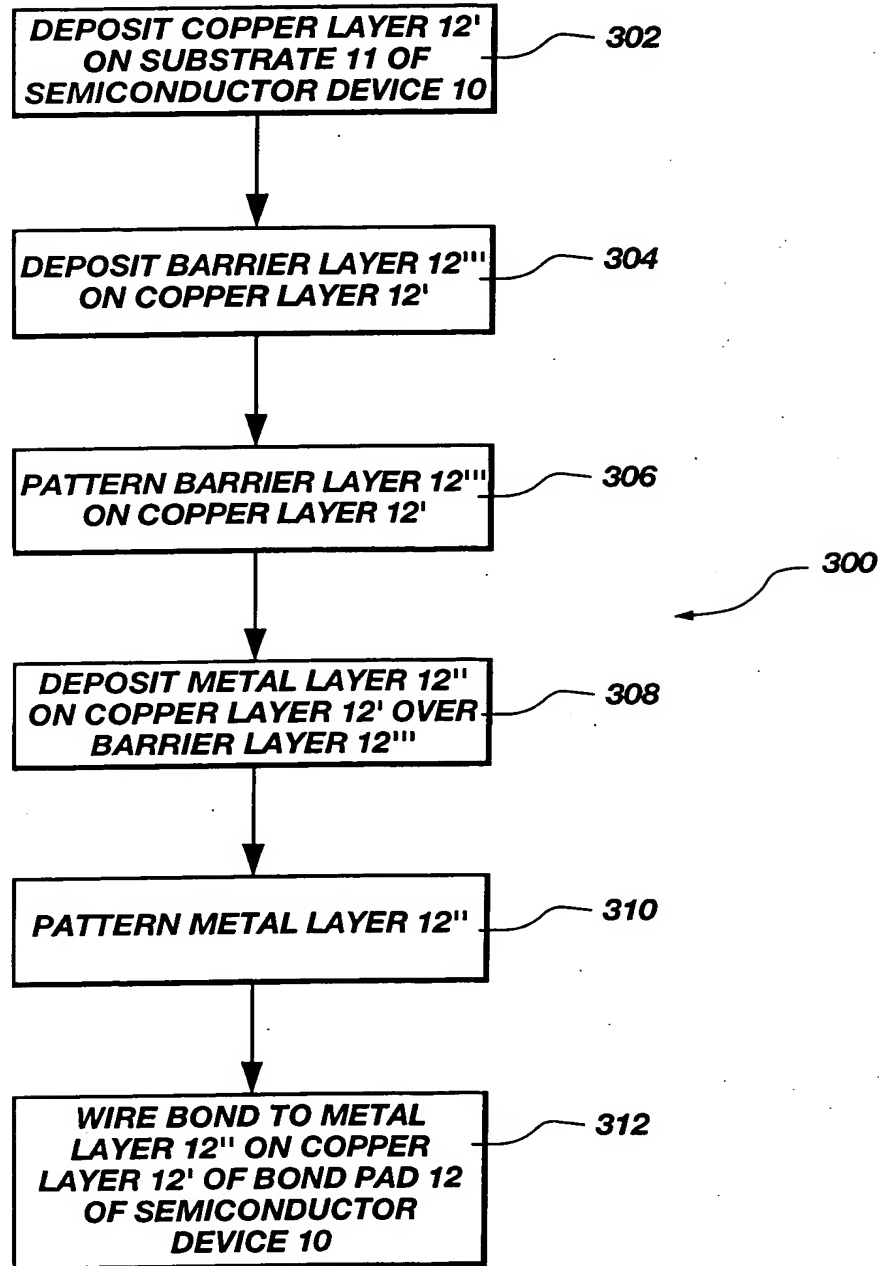


Fig. 5C

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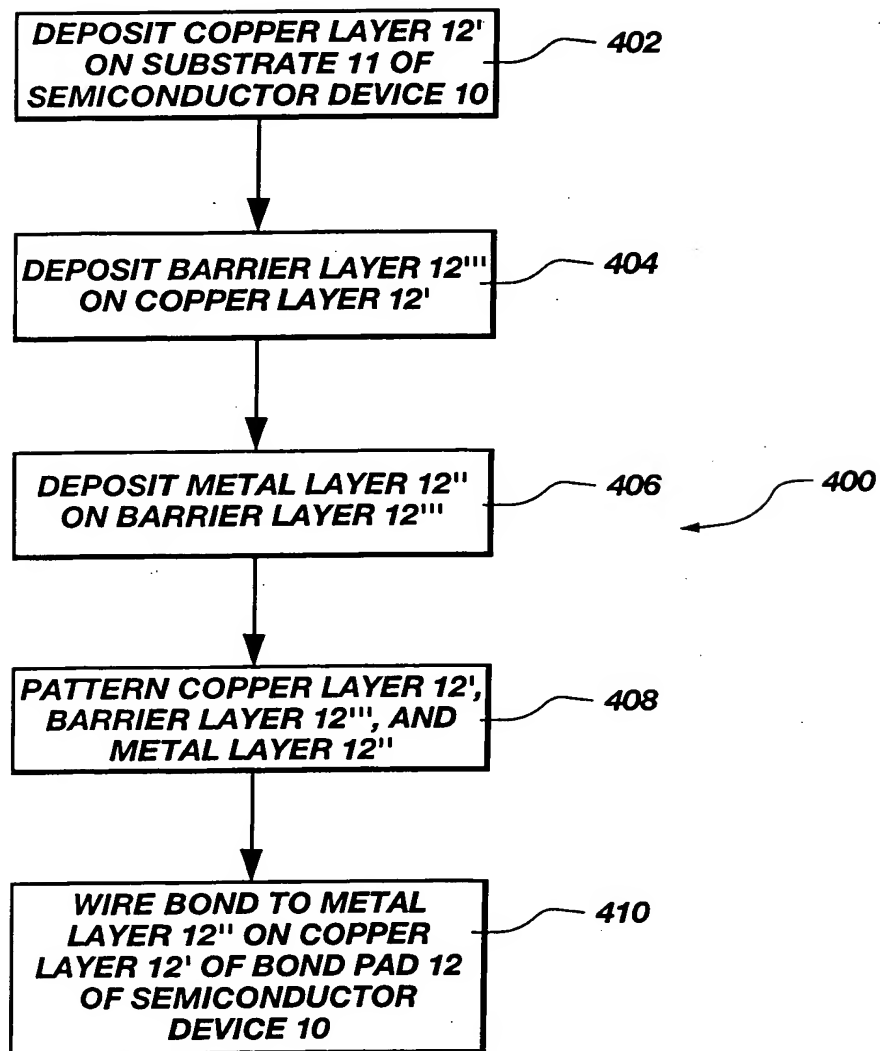


Fig. 5D

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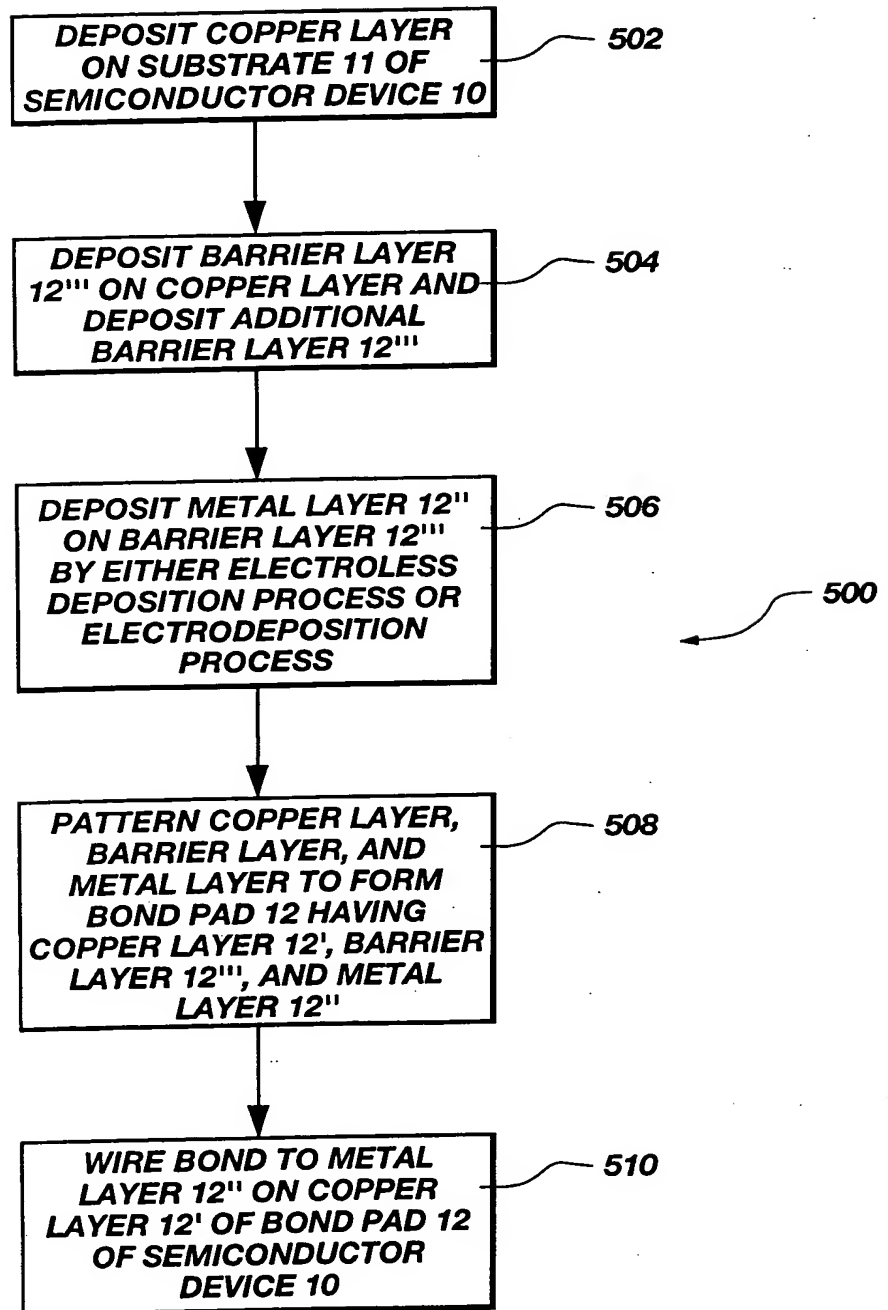


Fig. 5E

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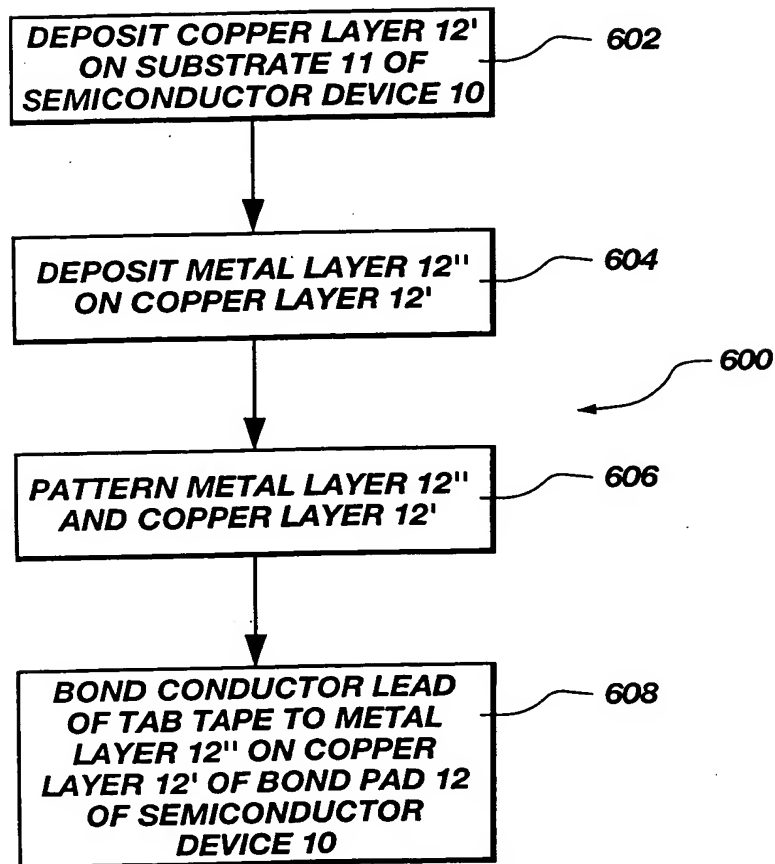


Fig. 5F

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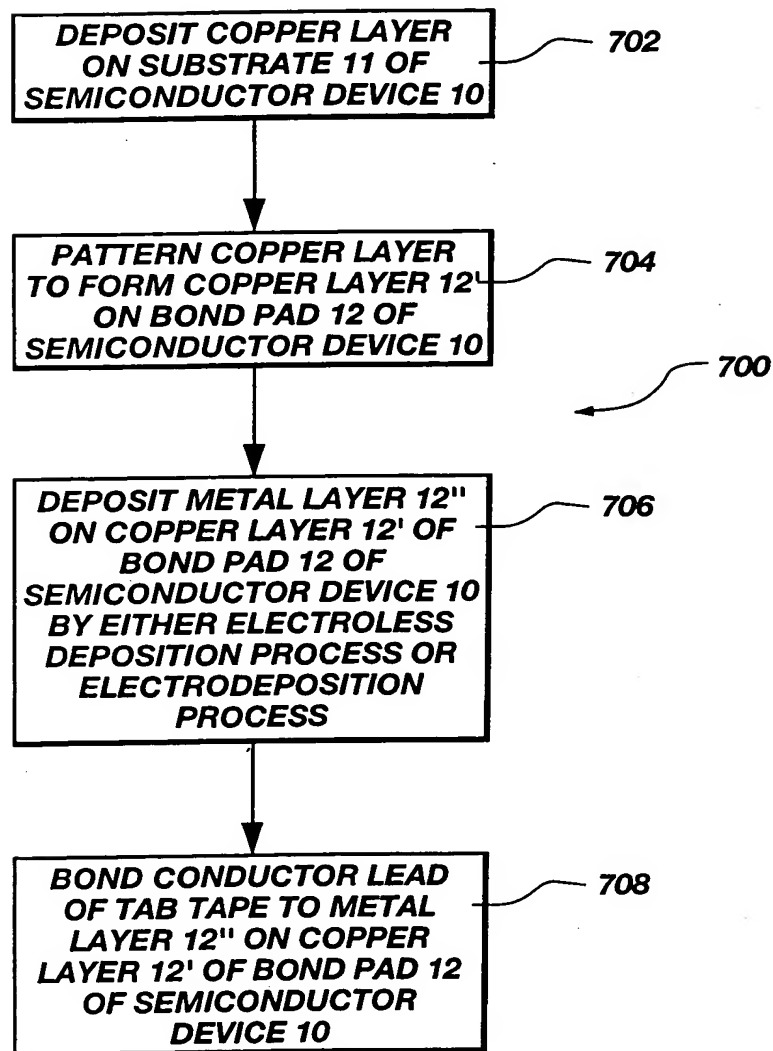


Fig. 5G

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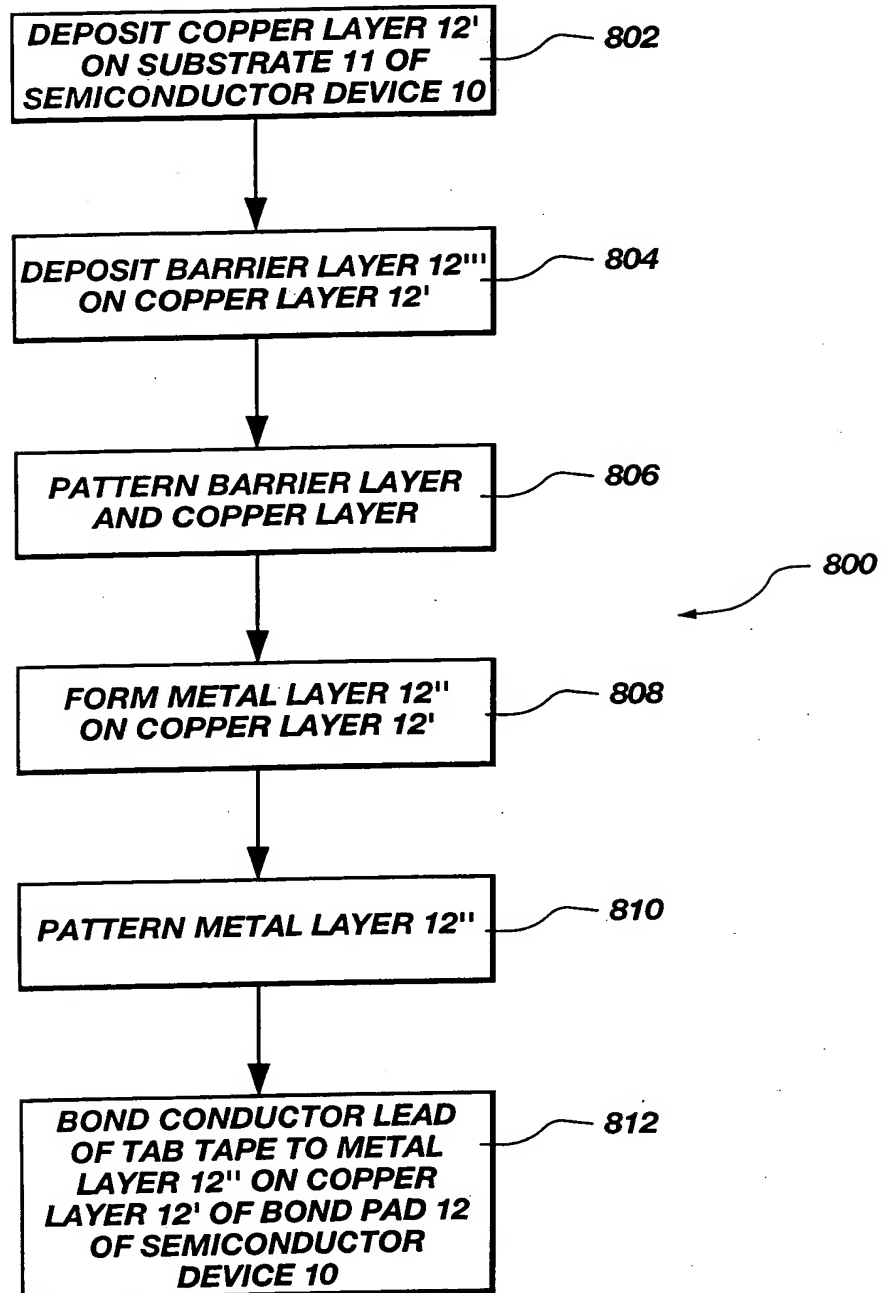


Fig. 5H

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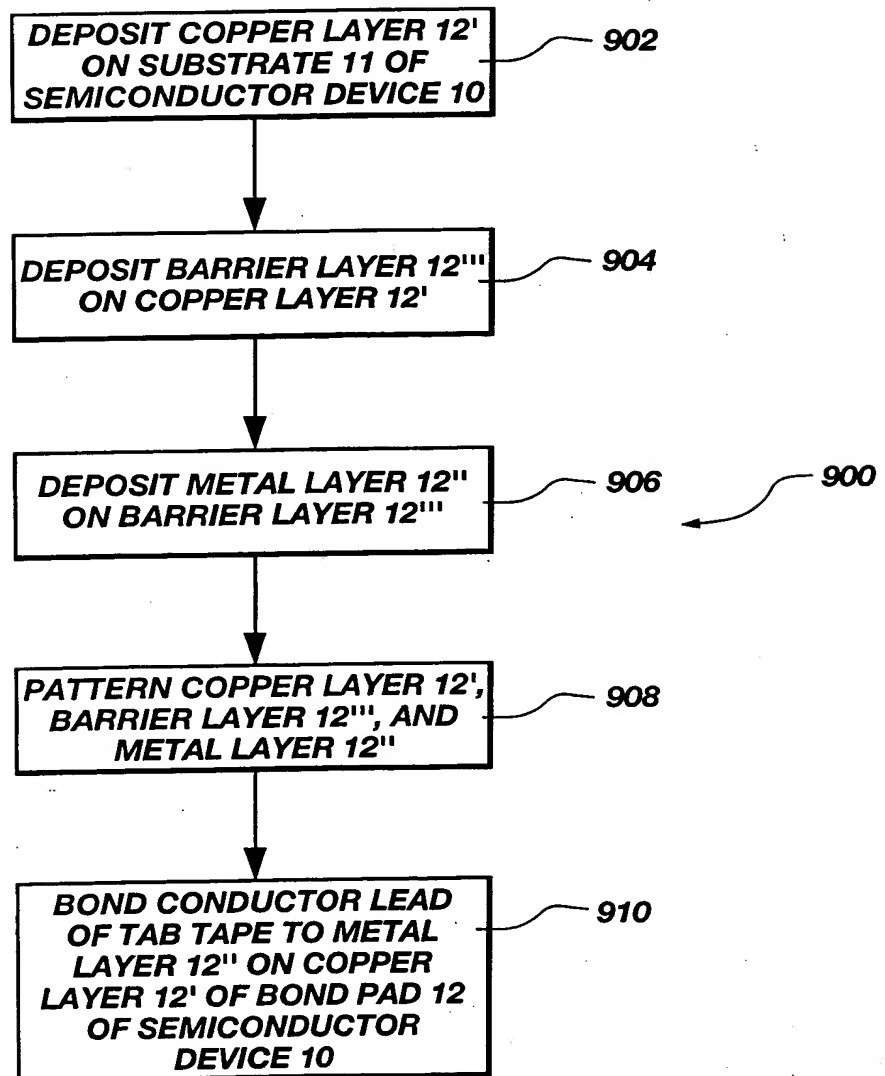


Fig. 5I

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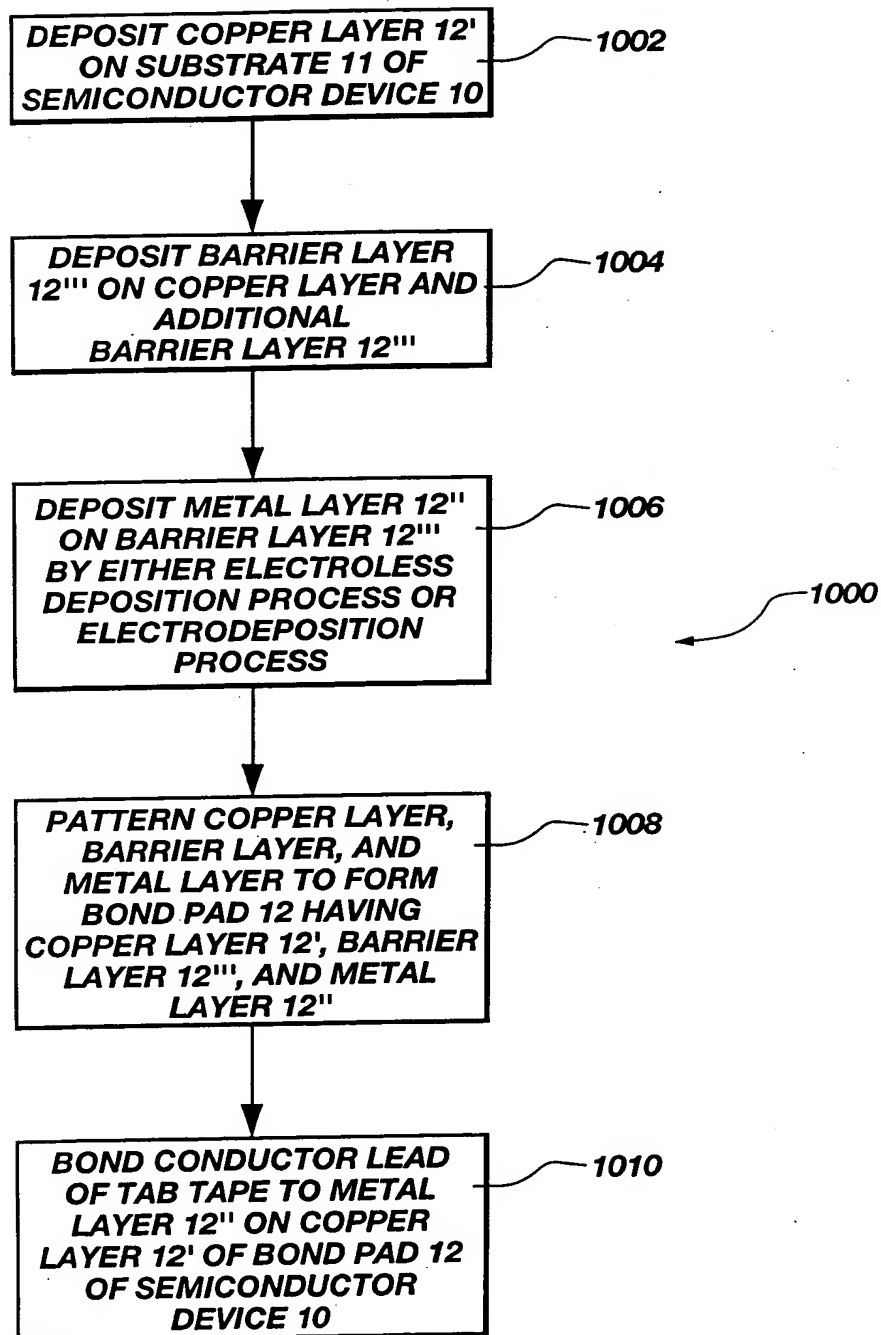


Fig. 5J